L Number	Hits	Search Text	DB	Time stamp
97	26		USPAT;	2004/04/29 12:00
		substrate and reflect\$4 and 349/\$.ccls. and	US-PGPUB;	
		metal and bond\$4 and mark	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
98	12		USPAT;	2004/04/29 12:01
		(substrate near10 bond\$4 near10 mark)and	US-PGPUB;	
		metal	EPO; JPO;	
			DERWENT; IBM TDB	
	1	JP07145688.ap.	USPAT; JPO	2003/12/30 11:43
_		JP06331208.ap.	USPAT; JPO	2003/12/26 13:30
_		349/158	USPAT;	2003/12/26 13:31
		319, 200	US-PGPUB;	,
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	627	((planar or flat\$4) near10 roughn\$4) and	USPAT;	2003/12/26 13:36
		substrate and reflect\$4	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	_	TRANSI 6005	IBM_TDB	2002/12/26 12:42
-	1	JP08216995.ap.	USPAT; US-PGPUB;	2003/12/26 13:43
i			EPO; JPO;	į
			DERWENT;	
			IBM TDB	
_	45	((planar or flat\$4) near10 roughn\$4) and	USPAT;	2003/12/26 13:52
		substrate and reflect\$4 and (liquid adj	US-PGPUB;	
		crystal) and align\$4 and mark	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	181	((planar or flat\$4) near10 roughn\$4) and	USPAT;	2004/04/28 16:05
		substrate and reflect\$4 and (liquid adj	US-PGPUB;	
		crystal)	EPO; JPO;	
			DERWENT; IBM TDB	
	95	349/113 and roughn\$4	USPAT;	2003/12/30 16:22
_	93	349/113 and loughnist	US-PGPUB;	2003, 12, 30 10.22
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	57	349/158 and roughn\$4	USPAT;	2003/12/29 16:55
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	20		IBM_TDB USPAT;	2003/12/29 17:24
_	20	process adj control adj mark	US-PGPUB;	2003/12/29 17:24
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	751	mean adj wavelength	USPAT;	2003/12/29 17:25
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
],	IBM_TDB	0000/10/00 == ==
-	5	\	USPAT;	2003/12/29 17:26
		rough\$4)	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
	55	(mean adj wavelength) and (liquid adj	USPAT;	2003/12/29 17:35
		crystal)	US-PGPUB;	
		,	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	1		USPAT	2003/12/29 17:35
-	4	,	USPAT	2003/12/30 08:43
		"6331882").PN.	L	

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-	63	(seal near10 (flat or planar))and 349/\$.ccls.	USPAT; US-PGPUB; JPO	2003/12/30 14:15
-	0	(seal near10 (flat or planar))and 349/\$.ccls and rough\$4.	USPAT; US-PGPUB;	2003/12/30 11:50
-	0	(seal near10 (flat or planar))and 349/\$.ccls and roughen\$4.	JPO USPAT; US-PGPUB;	2003/12/30 11:51
-	5	(seal near10 (flat or planar)) with roughen\$4	JPO USPAT; US-PGPUB;	2003/12/30 14:16
-	6	349/153 and (flat or planar) and roughen\$4	JPO USPAT; US-PGPUB;	2003/12/30 14:25
-	5953	seal\$4 and (flat or planar) and roughen\$4	JPO USPAT; US-PGPUB;	2003/12/30 14:25
-	0	(seal\$4 near10 (flat or planar)) and roughen\$4 and 349/\$ccls.	JPO USPAT; US-PGPUB;	2003/12/30 14:26
-	604	(seal\$4 near10 (flat or planar)) and roughen\$4	JPO USPAT; US-PGPUB;	2003/12/30 14:36
-	14	(seal\$4 near10 (flat or planar)) and roughen\$4 and 349/\$.ccls.	JPO USPAT; US-PGPUB;	2003/12/30 14:36
-	12	349/160 and roughn\$4	JPO USPAT; US-PGPUB;	2003/12/30 16:22
-	15	349/67 and roughn\$4	EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/12/30 16:22
-	24	((planar or flat\$4) near10 roughn\$4) and substrate and reflect\$4 and (liquid adj crystal) and metal and (alignment adj mark)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/04/28 16:13
-	178	((planar or flat\$4) near10 roughn\$4) and substrate and reflect\$4 and (liquid adj crystal) and metal	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/04/28 16:42
-	3	((planar or flat\$4) near10 roughn\$4 near10 metal) and substrate and reflect\$4 and (liquid adj crystal)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/04/28 16:20
-	21	((planar or flat\$4) near10 roughn\$4) and substrate and reflect\$4 and 349/\$.ccls. and metal	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/04/28 16:46
-	1	((planar or flat\$4) and roughn\$4) and substrate and reflect\$4 and 349/\$.ccls. and (metal near10 mark)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/04/28 16:47
-	175	((planar or flat\$4) and roughn\$4) and substrate and reflect\$4 and 349/\$.ccls. and metal	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/04/29 11:59
I			IBM_TDB	